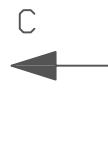
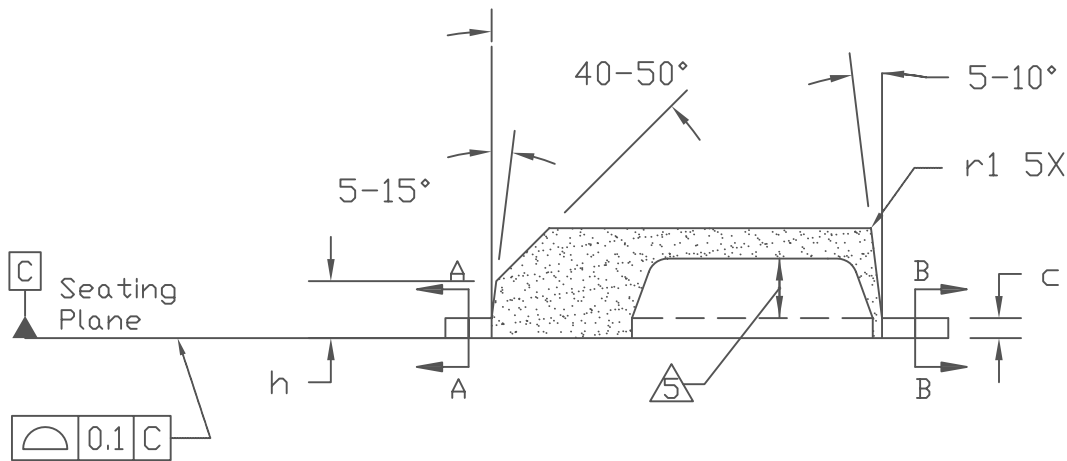
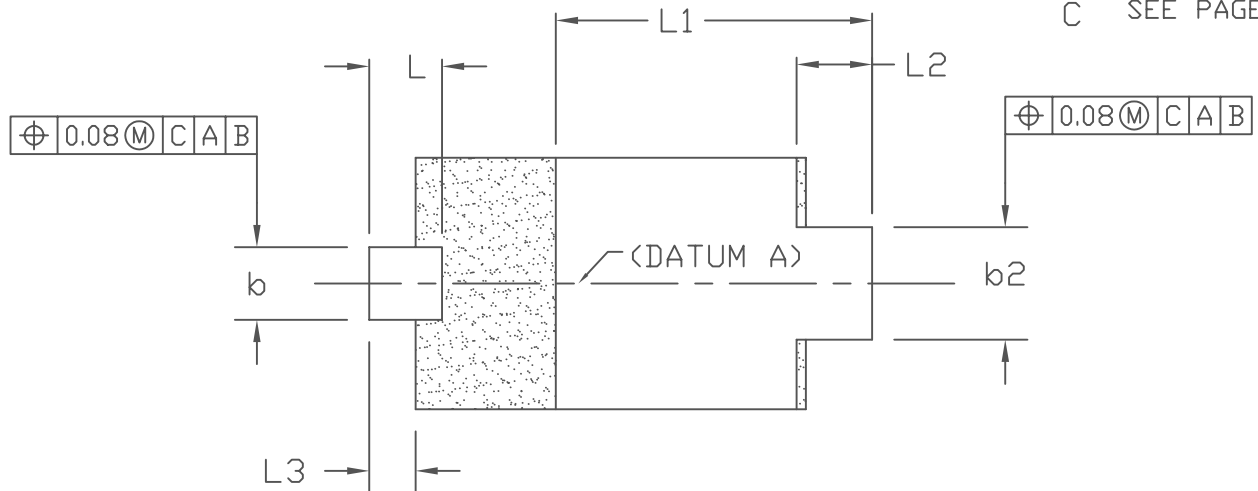


TOP VIEW



SEE PAGE 2



BOTTOM VIEW

JEDEC
SOLID STATE
PRODUCT OUTLINES

THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

TITLE: VERY THIN,
SMALL OUTLINE PLASTIC
SURFACE MOUNT PACKAGE

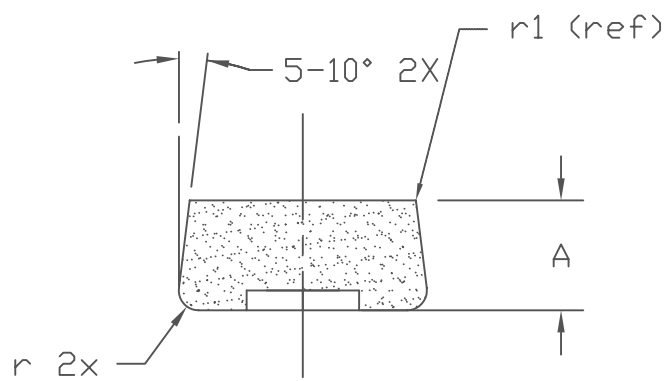
PACKAGE DESIGNATOR
V-PSDF

ISSUE
A

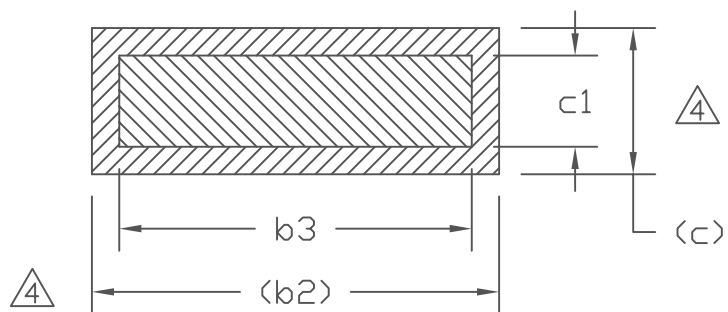
DATE
MAY 06

DO-222

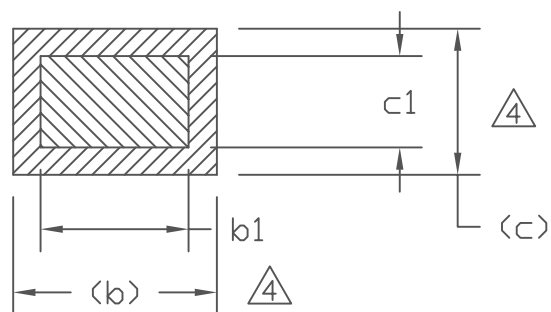
SHEET
1 OF 5



VIEW C-C



Section B-B



Section A-A

JEDEC SOLID STATE PRODUCT OUTLINES	TITLE: VERY THIN, SMALL OUTLINE PLASTIC SURFACE MOUNT PACKAGE	ISSUE A	DATE MAY 06	DO-222	SHEET 2 OF 5
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	VARIATIONS											
	AA											
	Min	Nom	Max	Note								
A	0.80	0.85	0.95									
b	0.40	–	0.65	4								
b1	0.40	0.55	0.65	4								
b2	0.70	–	1.00	4								
b3	0.70	0.85	0.95	4								
c	0.10	–	0.25	4								
c1	0.10	0.15	0.25	4								
D	1.75	1.90	2.05	3,5								
E	3.60	3.80	3.90									
E1	2.80	2.95	3.10	3,5								
h	0.35	0.45	0.50									
L	0.50	0.55	0.80									
L1	2.10	2.40	2.60									
L2	0.45	0.60	0.75									
L3	0.20	0.35	0.50									
r		0.150 (REF)										
r1	–	–	0.1									
Note												
Ref.	11.10-439											
Issue	A											
JEDEC SOLID STATE PRODUCT OUTLINES			TITLE: VERY THIN, SMALL OUTLINE PLASTIC SURFACE MOUNT PACKAGE					ISSUE A	DATE MAY 06	DD-222	SHEET 3 OF 5	

NOTES:

1 - Dimensioning and Tolerancing per ASME Y14.5M-1994

2 - All dimensions in millimeters

△3 - Dimensions D and E1 do not include mold flash
Mold flash shall not exceed 0.13mm per side

△4 - Dimensions b1, b3 and c1 apply to base metal only
Dimensions b, b2 and c apply to plated leads

△5 - The feature shown above the dashed line is optional.
In cases where the optional feature is missing the
termination of the exposed pad will coincide with dimension
'D'.

6 - STMicroelectronics Inc. has applied for patents that
may apply to this registration. If these patents or later
patents resulting from related applications do apply, this
company intends to comply with the JEDEC patent policy.

JEDEC SOLID STATE PRODUCT OUTLINES	TITLE: VERY THIN, SMALL OUTLINE PLASTIC SURFACE MOUNT PACKAGE	ISSUE A	DATE MAY 06	DO-222	SHEET 4 OF 5
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Change Record

If the change involves any words added or deleted (excluding deletion of accidentally repeated words), the change is to be included below. Punctuation changes may or may not be included.

Initial Issue: A	Date: May 2006	JC 11 Item Number :10-439

Change Record History

Issue:	Date :	Item Number
Location	Changed from:	Changed to:

Issue:	Date :	Item Number
Location	Changed from:	Changed to:

Issue:	Date :	Item Number
Location	Changed from:	Changed to: